

TAIWAN SEMICONDUCTOR MANUFACTURING CO LTD

Form 6-K

December 02, 2003

1934 Act Registration No. 1-14700

SECURITIES AND EXCHANGE
COMMISSION
Washington, DC 20549

FORM 6-K

REPORT OF FOREIGN PRIVATE ISSUER
PURSUANT TO RULE 13a-16 OR 15d-16 OF
THE SECURITIES EXCHANGE ACT OF 1934

For the month of December 2003

Taiwan Semiconductor Manufacturing Company Ltd.
(Translation of Registrant's Name Into English)

No.8 Li-Hsin Rd. 6,
Science Park
Hsin-chu, Taiwan
(Address of Principal Executive Offices)

(Indicate by check mark whether the registrant files or will file
annual reports under cover of Form 20-F or Form 40-F.)

Form 20-F X

Form 40-F

(Indicate by check mark whether the registrant by furnishing the
information contained in this form is also thereby furnishing the information to
the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of
1934.)

Yes

No X

(If "Yes" is marked, indicated below the file number assigned to the registrant
in connection with Rule 12g3-2(b): 82: _____.)

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934,
the registrant has duly caused this report to be signed on its behalf by the
undersigned, thereunto duly authorized.

Taiwan Semiconductor Manufacturing Company Ltd.

Date: December 2, 2003

By /s/ Lora Ho

Lora Ho
Vice President & Chief Financial Officer

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TSMC Board of Directors Approves Plans to Expand 300mm Wafer and Advanced Technology Capacity

Hsinchu, Taiwan, December 2, 2003 - Taiwan Semiconductor Manufacturing Company Ltd. (TSMC or the "Company") (NYSE: TSM) today held a meeting of the Board of Directors, at which the Board approved a capital appropriation in the amount of US\$1,427,600,000 for capacity expansion plans to accommodate customers' advanced process technology demands. The appropriation is mainly targeted toward expanding production capacity for the Company's 0.13-micron and 90-nanometer copper processes at its Fab 12 (Phase I) and Fab 14 (Phase I) 300mm production facilities. In addition, part of this appropriation is targeted at increasing the Company's 0.18-micron and 0.15-micron process capacity at some of its eight-inch fabs.

Ms. Lora Ho, TSMC spokesperson, vice president and chief financial officer noted that, the appropriation is not reflective of TSMC's annual capex for 2004. The Company expects to announce its 2004 capex early next year.

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TSMC Spokesperson:

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